



Part No. 96-160M65 - QFP to PGA Adapter for 160 Position, .0256 [.65] Pitch

FEATURES:

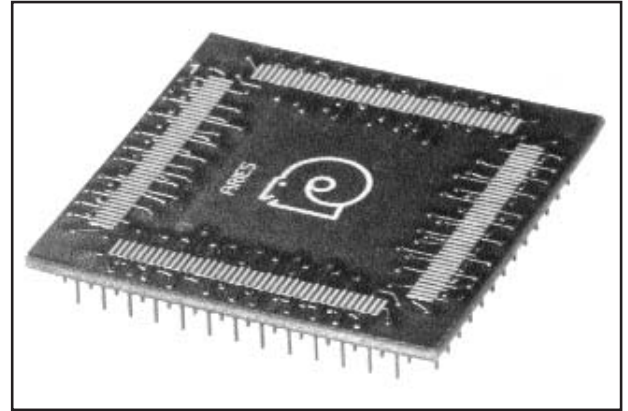
- Convert surface mount QFP packages to a 15 x 15 PGA footprint.
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for panelized form or for mounting of con-signed chips.

SPECIFICATIONS:

- Adapter body is FR-4 with 1 ounce minimum Copper traces.
- Pads are finished with ENIG (Immersion Gold over Electroless Nickel).
- Pins are Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-00.
- Pin plating is 200 μ [5.08 μ m] min. Tin per ASTM B 545 Type 1 or Tin/Lead 93/7 per ASTM B 545 over 100 μ [2.54 μ m] Nickel per SAE-AMS-QQ-N-290.
- Operating temperature=221°F [105°C].

MOUNTING CONSIDERATIONS:

- Suggested PCB hole size=.028 \pm .003 [.71 \pm .08] dia.
- Will plug into standard PGA sockets.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

Specify Part No. 96-160M65

-or-

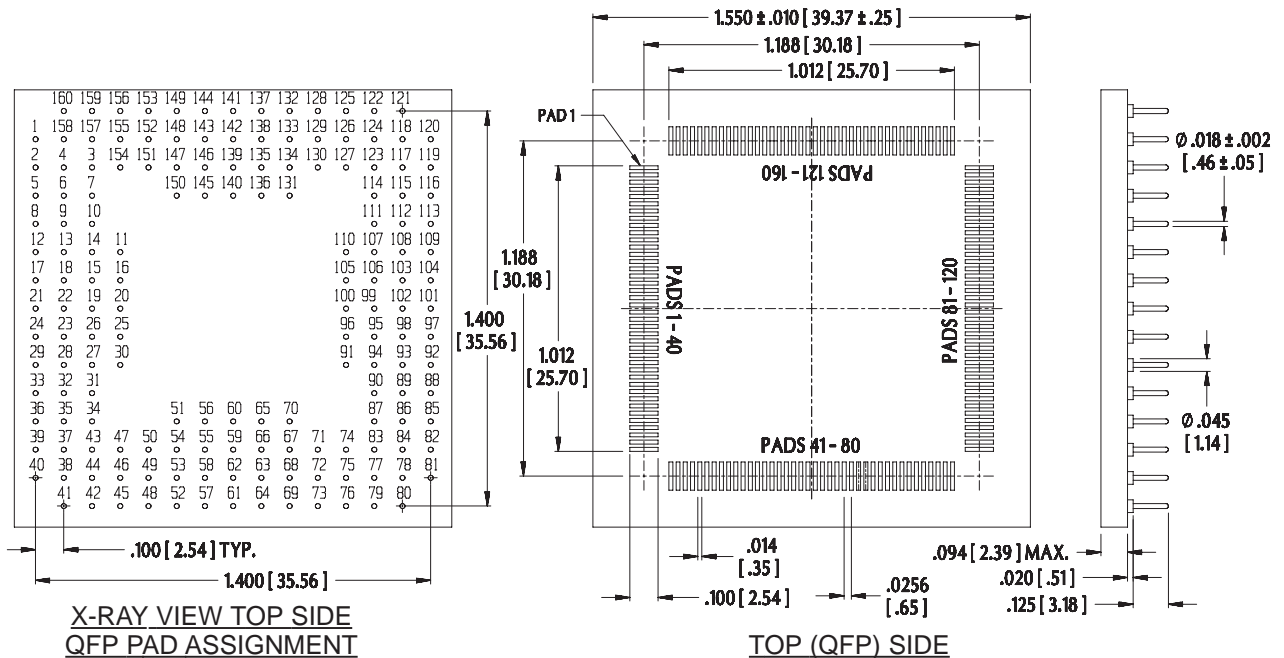
96-160M65-P for panelized form when ordering

Specify Part Number 160-PGM15043-30 for wire wrap PGA socket

ALL DIMENSIONS: INCHES [MILLIMETERS]

Tolerances:

- Row-to-row: \pm .003 [\pm .08]
- Pin-to-pin: \pm .003 [\pm .08] non-cumulative
- All others: \pm .005 [.13] unless otherwise specified



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